Lattice Semiconductor Corporation - LFXP20E-4F484C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	20000
Total RAM Bits	405504
Number of I/O	340
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp20e-4f484c

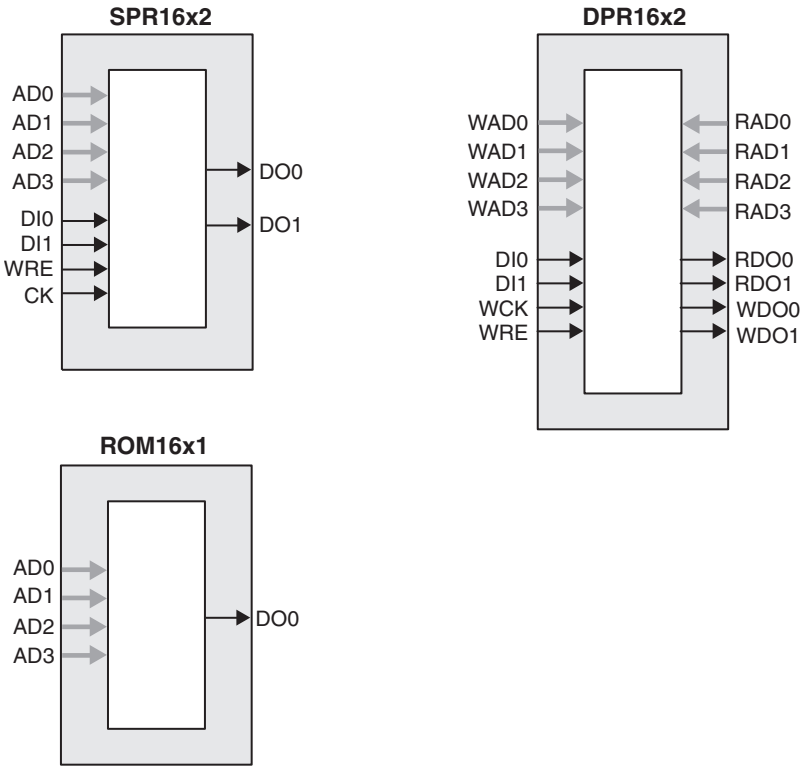
The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-4 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode in LatticeXP devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required for Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Figure 2-4. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Figure 2-21. Input Register DDR Waveforms

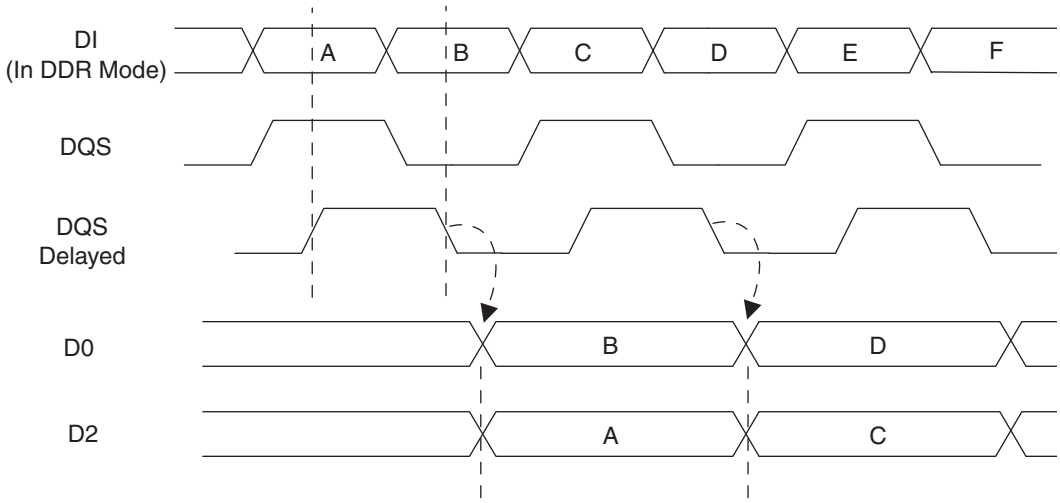
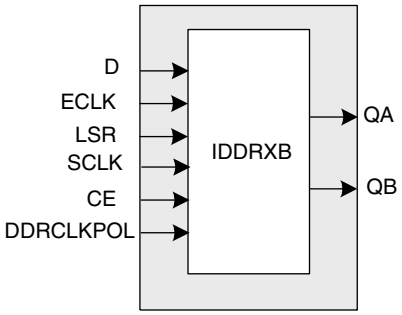


Figure 2-22. INDDRXB Primitive



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-23 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type or as a latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-24 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Figure 2-26. DQS Local Bus

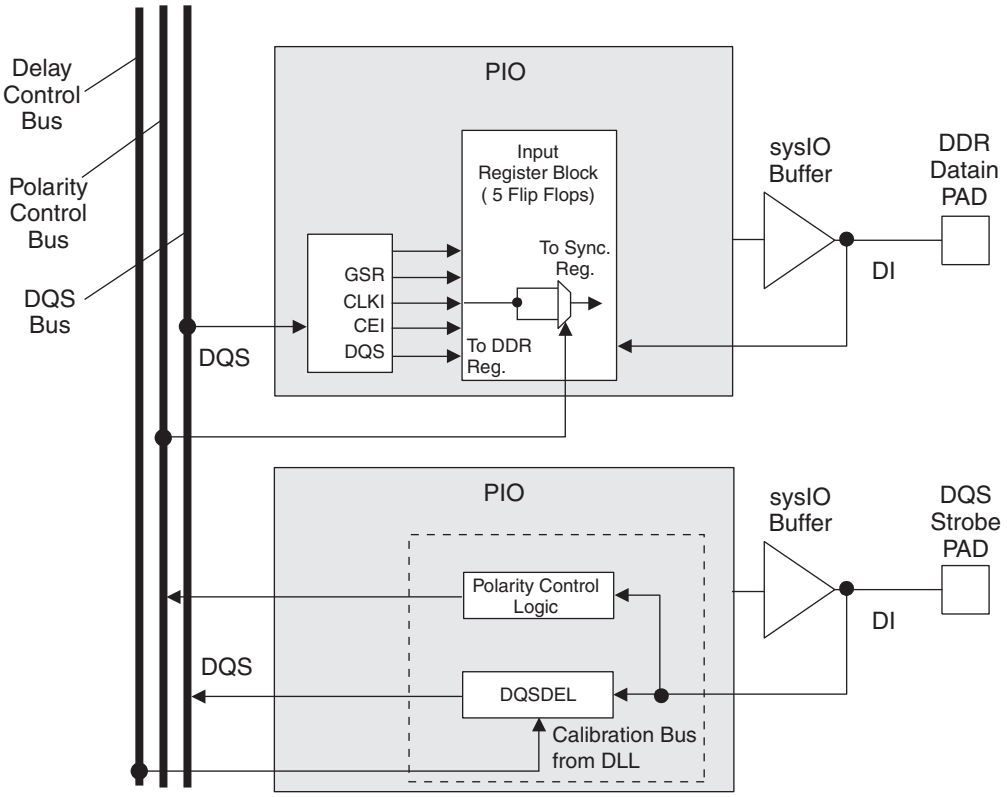
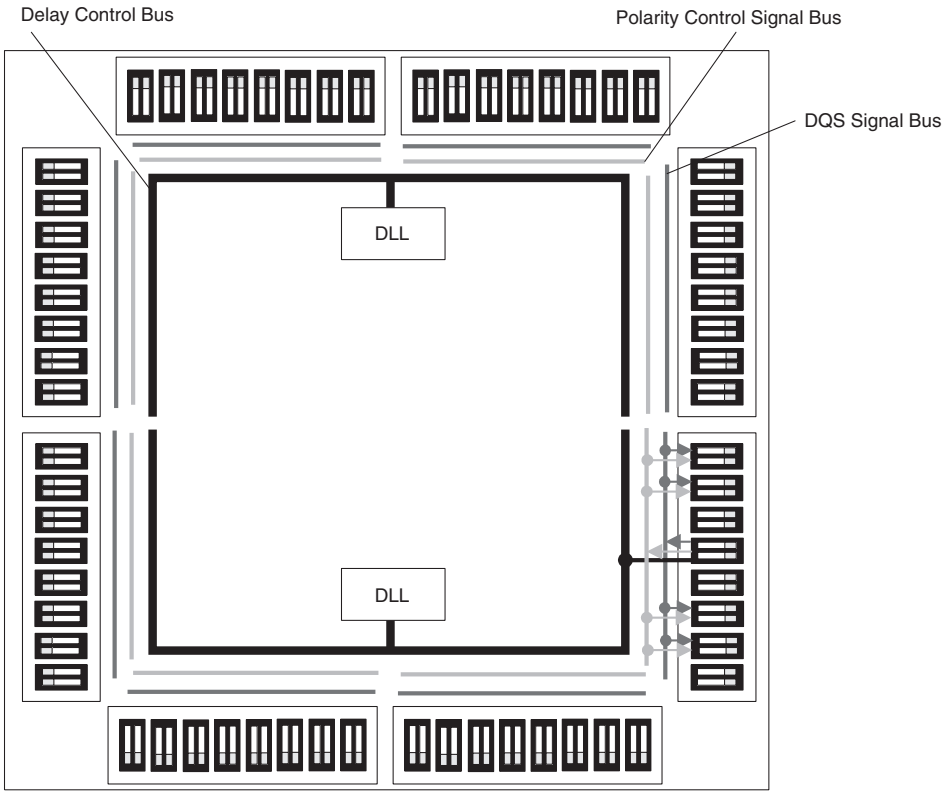


Figure 2-27. DLL Calibration Bus and DQS/DQS Transition Distribution



Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will not take on the user configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The LatticeXP sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, differential SSTL and differential HSTL. Tables 2-7 and 2-8 show the I/O standards (together with their supply and reference voltages) supported by the LatticeXP devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Table 2-7. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33[2]	—	—
LVCMOS25[2]	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12[2]	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
Differential Interfaces		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL	—	—
BLVDS	—	—

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.
2. JTAG inputs do not have a fixed threshold option and always follow V_{CCJ}.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LFXP3E	15	mA
		LFXP6E	20	mA
		LFXP10E	35	mA
		LFXP15E	45	mA
		LFXP20E	55	mA
		LFXP3C	35	mA
		LFXP6C	40	mA
		LFXP10C	70	mA
		LFXP15C	80	mA
		LFXP20C	90	mA
I_{CCP}	PLL Power Supply (per PLL)	All	8	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	22	mA
		LFXP6E/C	22	mA
		LFXP10E/C	30	mA
		LFXP15E/C	30	mA
		LFXP20E/C	30	mA
I_{CCIO}	Bank Power Supply[6]	All	2	mA
I_{CCJ}	V_{CCJ} Power Supply	All	1	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the VCCIO or GND.
3. Frequency 0MHz.
4. User pattern: blank.
5. T_A=25°C, power supplies at nominal voltage.
6. Per bank.

Initialization Supply Current[1, 2, 3, 4, 5, 6]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[7]	Units
I_{CC}	Core Power Supply	LFXP3E	40	mA
		LFXP6E	50	mA
		LFXP10E	110	mA
		LFXP15E	140	mA
		LFXP20E	250	mA
		LFXP3C	60	mA
		LFXP6C	70	mA
		LFXP10C	150	mA
		LFXP15C	180	mA
		LFXP20C	290	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15 /C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply	All	2	mA

1. Until DONE signal is active.
2. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. Typical user pattern.
6. Assume normal bypass capacitor/decoupling capacitor across the supply.
7. T_A=25°C, power supplies at nominal voltage.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCIO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCIO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCIO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCIO} - 0.43	15.2	-15.2
SSTL18 class I	-0.3	V_{REF} - 0.125	V_{REF} + 0.125	3.6	0.4	V_{CCIO} - 0.4	6.7	-6.7
HSTL15 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	8	-8
HSTL15 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8
HSTL18 class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	9.6	-9.6
HSTL18 class II	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	16	-16
HSTL18 class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCIO} - 0.4	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

LVPECL

The LatticeXP devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

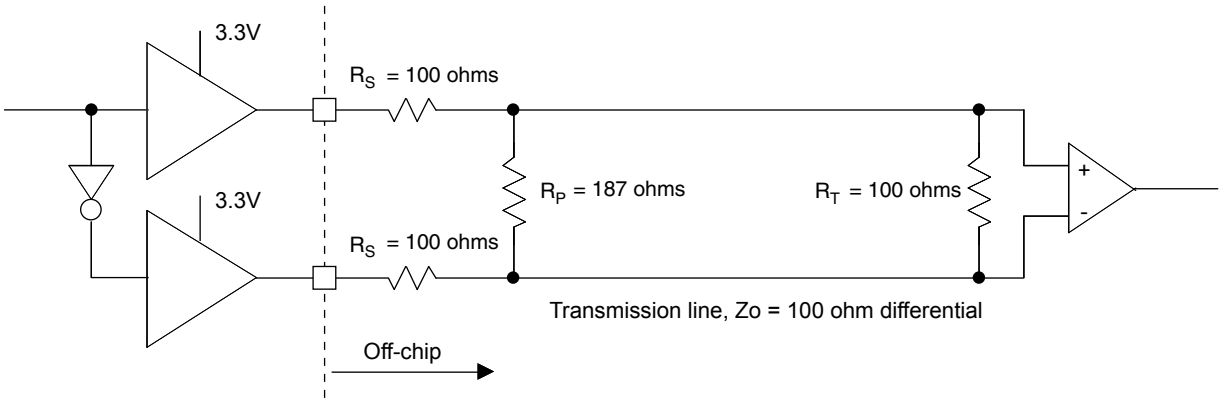


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Typical	Units
Z_{OUT}	Output impedance	100	ohms
R_P	Driver parallel resistor	187	ohms
R_S	Driver series resistor	100	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The LatticeXP devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

LatticeXP External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}	Clock to Output - PIO Output Register	LFXP3	—	5.12	—	6.12	—	7.43	ns
		LFXP6	—	5.30	—	6.34	—	7.69	ns
		LFXP10	—	5.52	—	6.60	—	8.00	ns
		LFXP15	—	5.72	—	6.84	—	8.29	ns
		LFXP20	—	5.97	—	7.14	—	8.65	ns
t_{SU}	Clock to Data Setup - PIO Input Register	LFXP3	-0.40	—	-0.28	—	-0.16	—	ns
		LFXP6	-0.33	—	-0.32	—	-0.30	—	ns
		LFXP10	-0.61	—	-0.71	—	-0.81	—	ns
		LFXP15	-0.71	—	-0.77	—	-0.87	—	ns
		LFXP20	-0.95	—	-1.14	—	-1.35	—	ns
t_{H}	Clock to Data Hold - PIO Input Register	LFXP3	2.10	—	2.50	—	2.98	—	ns
		LFXP6	2.28	—	2.72	—	3.24	—	ns
		LFXP10	3.02	—	3.51	—	3.71	—	ns
		LFXP15	2.70	—	3.22	—	3.85	—	ns
		LFXP20	2.95	—	3.52	—	4.21	—	ns
t_{SU_DEL}	Clock to Data Setup - PIO Input Register with Input Data Delay	LFXP3	2.38	—	2.49	—	2.66	—	ns
		LFXP6	2.92	—	3.18	—	3.42	—	ns
		LFXP10	2.72	—	2.75	—	2.84	—	ns
		LFXP15	2.99	—	3.13	—	3.18	—	ns
		LFXP20	4.47	—	4.56	—	4.80	—	ns
t_{H_DEL}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFXP3	-0.70	—	-0.80	—	-0.92	—	ns
		LFXP6	-0.47	—	-0.38	—	-0.31	—	ns
		LFXP10	-0.60	—	-0.47	—	-0.32	—	ns
		LFXP15	-1.05	—	-0.98	—	-1.01	—	ns
		LFXP20	-0.80	—	-0.58	—	-0.31	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All	—	400	—	360	—	320	MHz
DDR I/O Pin Parameters[2]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	166	95	133	95	100	MHz
Primary and Secondary Clocks									
f_{MAX_PRI}	Frequency for Primary Clock Tree	All	—	450	—	412	—	375	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	LFXP3/6/10/15	—	250	—	300	—	350	ps
		LFXP20	—	300	—	350	—	400	ps

1. General timing numbers based on LVCMOS 2.5, 12mA.
2. DDR timing numbers based on SSTL I/O.

Timing v.F0.11

LatticeXP Family Timing Adders[1] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTL33_4mA	LVTTL 4mA drive	0.8	0.8	0.8	ns
LVTTL33_8mA	LVTTL 8mA drive	0.5	0.5	0.5	ns
LVTTL33_12mA	LVTTL 12mA drive	0.3	0.3	0.3	ns
LVTTL33_16mA	LVTTL 16mA drive	0.4	0.4	0.4	ns
LVTTL33_20mA	LVTTL 20mA drive	0.3	0.3	0.3	ns
LVCMOS33_2mA	LVCMOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVCMOS25_2mA	LVCMOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVCMOS18_2mA	LVCMOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVCMOS15_2mA	LVCMOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVCMOS 2.5, 12mA.

Timing v.F0.11

sysCLOCK PLL Timing

Over Recommended Operating Conditions

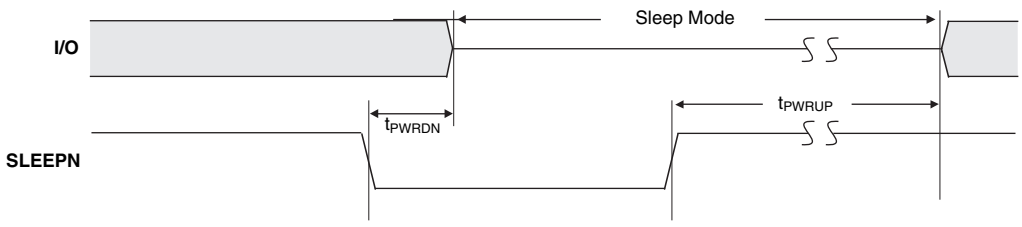
Parameter	Descriptions	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	—	375	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	—	375	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	—	187.5	MHz
f_{VCO}	PLL VCO Frequency		375	—	750	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	—	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default duty cycle elected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	f_{OUT} Š 100MHz	—	—	+/- 125	ps
		f_{OUT} < 100MHz	—	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	—	+/- 200	ps
t_W	Output Clock Pulse Width	At 90% or 10%[3]	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time		—	—	150	us
t_{PA}	Programmable Delay Unit		100	250	400	ps
t_{IPJIT}	Input Clock Period Jitter		—	—	+/- 200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width		10	—	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. As compared to CLKOP output.

Timing v.F0.11

LatticeXP "C" Sleep Mode Timing

Parameter	Descriptions		Min.	Typ.	Max.	Units
t_{PWRDN}	SLEEPN Low to I/O Tristate		—	20	32	ns
t_{PWRUP}	SLEEPN High to Power Up	LFXP3	—	1.4	2.1	ms
		LFXP6	—	1.7	2.4	ms
		LFXP10	—	1.1	1.8	ms
		LFXP15	—	1.4	2.1	ms
		LFXP20	—	1.7	2.4	ms
$t_{WSLEEPN}$	SLEEPN Pulse Width to Initiate Sleep Mode		400	—	—	ns
t_{WAWAKE}	SLEEPN Pulse Rejection		—	—	120	ns



Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

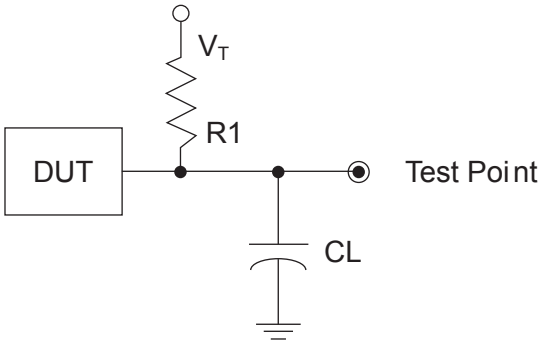


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

PICs and DDR Data (DQ) Pins Associated with the DDR Strobe (DQS) Pin

PICs Associated with DQS Strobe	PIO within PIC	Polarity	DDR Strobe (DQS) and Data (DQ) Pins
P[Edge] [n-4]	A	True	DQ
	B	Complement	DQ
P[Edge] [n-3]	A	True	DQ
	B	Complement	DQ
P[Edge] [n-2]	A	True	DQ
	B	Complement	DQ
P[Edge] [n-1]	A	True	DQ
P[Edge] [n]			
	B	Complement	DQ
P[Edge] [n+1]	A	True	[Edge]DQSn
	B	Complement	DQ
P[Edge] [n+2]	A	True	DQ
	B	Complement	DQ
P[Edge] [n+3]	A	True	DQ
	B	Complement	DQ

Notes:
1. “n” is a row/column PIC number.
2. The DDR interface is designed for memories that support one DQS strobe per eight bits of data. In some packages, all the potential DDR data (DQ) pins may not be available.
3. The definition of the PIC numbering is provided in the Signal Names column of the Signal Descriptions table in this data sheet.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
1	PROGRAMN	7	-	-	PROGRAMN	7	-	-
2	CCLK	7	-	-	CCLK	7	-	-
3	GND	-	-	-	GND	-	-	-
4	PL2A	7	T[3]	-	PL2A	7	T[3]	-
5	PL2B	7	C[3]	-	PL2B	7	C[3]	-
6	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
7	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
8	VCCIO7	7	-	-	VCCIO7	7	-	-
9	PL5A	7	-	VREF1_7	PL5A	7	-	VREF1_7
10	PL6B	7	-	VREF2_7	PL6B	7	-	VREF2_7
11	GNDIO7	7	-	-	GNDIO7	7	-	-
12	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
13	PL7B	7	C[3]	-	PL7B	7	C[3]	-
14	VCC	-	-	-	VCC	-	-	-
15	PL8A	7	T	LUM0_PLLT_IN_A	PL8A	7	T	LUM0_PLLT_IN_A
16	PL8B	7	C	LUM0_PLLC_IN_A	PL8B	7	C	LUM0_PLLC_IN_A
17	PL9A	7	T[3]	-	PL9A	7	T[3]	-
18	PL9B	7	C[3]	-	PL9B	7	C[3]	-
19	VCCP0	-	-	-	VCCP0	-	-	-
20	GNDP0	-	-	-	GNDP0	-	-	-
21	VCCIO6	6	-	-	VCCIO6	6	-	-
22	PL11A	6	T[3]	-	PL16A	6	T[3]	-
23	PL11B	6	C[3]	-	PL16B	6	C[3]	-
24	PL12A	6	T	PCLKT6_0	PL17A	6	T	PCLKT6_0
25	PL12B	6	C	PCLKC6_0	PL17B	6	C	PCLKC6_0
26	PL13A	6	T[3]	-	PL18A	6	T[3]	-
27	PL13B	6	C[3]	-	PL18B	6	C[3]	-
28	GNDIO6	6	-	-	GNDIO6	6	-	-
29	PL14A	6	-	VREF1_6	PL22A	6	-	VREF1_6
30	PL15B	6	-	VREF2_6	PL23B	6	-	VREF2_6
31	PL16A	6	T[3]	DQS	PL24A	6	T[3]	DQS
32	PL16B	6	C[3]	-	PL24B	6	C[3]	-
33	PL17A	6	-	-	PL25A	6	-	-
34	PL18A	6	T[3]	-	PL26A	6	T[3]	-
35	PL18B	6	C[3]	-	PL26B	6	C[3]	-
36	VCCAUX	-	-	-	VCCAUX	-	-	-
37	SLEEPN[1]/TOE[2]	-	-	-	SLEEPN[1]/TOE[2]	-	-	-
38	INITN	5	-	-	INITN	5	-	-
39	VCC	-	-	-	VCC	-	-	-
40	PB2B	5	-	VREF1_5	PB5B	5	-	VREF1_5
41	PB5B	5	-	VREF2_5	PB8B	5	-	VREF2_5
42	PB7A	5	T	-	PB10A	5	T	-
43	PB7B	5	C	-	PB10B	5	C	-
44	GNDIO5	5	-	-	GNDIO5	5	-	-
45	PB9A	5	-	-	PB12A	5	-	-
46	PB10B	5	-	-	PB13B	5	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
C2	PROGRAMN	7	-	-	PROGRAMN	7	-	-
C1	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
D3	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
D1	PL2A	7	T[3]	-	PL5A	7	-	-
E2	PL5A	7	-	VREF1_7	PL6B	7	-	VREF1_7
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
F1	PL7B	7	C[3]	-	PL7B	7	C[3]	-
E3	PL12A	7	T	-	PL8A	7	T	-
F4	PL12B	7	C	-	PL8B	7	C	-
F3	PL4A	7	T[3]	-	PL9A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL9B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G1	PL2B	7	C[3]	-	PL11B	7	-	-
G3	PL8A	7	T	LUM0_PLLT_IN_A	PL12A	7	T	LUM0_PLLT_IN_A
G2	PL8B	7	C	LUM0_PLLC_IN_A	PL12B	7	C	LUM0_PLLC_IN_A
H1	PL9A	7	T[3]	-	PL13A	7	T[3]	-
H2	PL9B	7	C[3]	-	PL13B	7	C[3]	-
G4	PL6B	7	-	VREF2_7	PL14A	7	-	VREF2_7
G5	PL14A	7	-	-	PL15B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J1	PL11A	7	T[3]	-	PL16A	7	T[3]	DQS
J2	PL11B	7	C[3]	-	PL16B	7	C[3]	-
H3	PL13A	7	T[3]	-	PL18A	7	T[3]	-
J3	PL13B	7	C[3]	-	PL18B	7	C[3]	-
H4	VCCP0	-	-	-	VCCP0	-	-	-
H5	GNDP0	-	-	-	GNDP0	-	-	-
K1	PL17A	6	T	PCLKT6_0	PL20A	6	T	PCLKT6_0
K2	PL17B	6	C	PCLKC6_0	PL20B	6	C	PCLKC6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
J4	PL15B	6	-	-	PL22A	6	-	-
J5	PL22A	6	-	VREF1_6	PL23B	6	-	VREF1_6
L1	PL16A	6	T[3]	-	PL24A	6	T[3]	DQS
L2	PL16B	6	C[3]	-	PL24B	6	C[3]	-
M1	PL18A	6	T[3]	-	PL25A	6	T	LLM0_PLLT_IN_A
M2	PL18B	6	C[3]	-	PL25B	6	C	LLM0_PLLC_IN_A
K3	PL19A	6	T[3]	-	PL26A	6	T[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L3	PL19B	6	C[3]	-	PL26B	6	C[3]	-
L4	PL21A	6	T[3]	-	PL28A	6	-	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
C2	PROGRAMN	7	-	-	PROGRAMN	7	-	-
C1	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL7A	7	T	LUM0_PLLT_FB_A	PL7A	7	T	LUM0_PLLT_FB_A
D3	PL7B	7	C	LUM0_PLLC_FB_A	PL7B	7	C	LUM0_PLLC_FB_A
D1	PL9A	7	-	-	PL9A	7	-	-
E2	PL10B	7	-	VREF1_7	PL10B	7	-	VREF1_7
E1	PL11A	7	T[3]	DQS	PL11A	7	T[3]	DQS
F1	PL11B	7	C[3]	-	PL11B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E3	PL12A	7	T	-	PL12A	7	T	-
F4	PL12B	7	C	-	PL12B	7	C	-
F3	PL13A	7	T[3]	-	PL13A	7	T[3]	-
F2	PL13B	7	C[3]	-	PL13B	7	C[3]	-
G1	PL15B	7	-	-	PL15B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G3	PL16A	7	T	LUM0_PLLT_IN_A	PL16A	7	T	LUM0_PLLT_IN_A
G2	PL16B	7	C	LUM0_PLLC_IN_A	PL16B	7	C	LUM0_PLLC_IN_A
H1	PL17A	7	T[3]	-	PL17A	7	T[3]	-
H2	PL17B	7	C[3]	-	PL17B	7	C[3]	-
G4	PL18A	7	-	VREF2_7	PL18A	7	-	VREF2_7
G5	PL19B	7	-	-	PL19B	7	-	-
J1	PL20A	7	T[3]	DQS	PL20A	7	T[3]	DQS
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J2	PL20B	7	C[3]	-	PL20B	7	C[3]	-
H3	PL22A	7	T[3]	-	PL22A	7	T[3]	-
J3	PL22B	7	C[3]	-	PL22B	7	C[3]	-
H4	VCCP0	-	-	-	VCCP0	-	-	-
H5	GNDP0	-	-	-	GNDP0	-	-	-
K1	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K2	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
J4	PL26A	6	-	-	PL30A	6	-	-
J5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
L1	PL28A	6	T[3]	DQS	PL32A	6	T[3]	DQS
L2	PL28B	6	C[3]	-	PL32B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
M1	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
M2	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
K3	PL30A	6	T[3]	-	PL34A	6	T[3]	-
L3	PL30B	6	C[3]	-	PL34B	6	C[3]	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
G7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
G10	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G9	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
H8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G13	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G14	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
J16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
K16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
N16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
P16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T13	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T14	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
R8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T10	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T9	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
N7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
P7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
R7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
H7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
J7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
K7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
D18	-	-	-	-	PT55B	1	C	-
E18	-	-	-	-	PT55A	1	T	-
C19	-	-	-	-	PT54B	1	C	-
C18	-	-	-	-	PT54A	1	T	-
C21	-	-	-	-	PT53B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B21	-	-	-	-	PT53A	1	T	-
E17	PT48B	1	C	-	PT52B	1	C	-
E16	PT48A	1	T	-	PT52A	1	T	-
C17	PT47B	1	C	-	PT51B	1	C	-
D17	PT47A	1	T	DQS	PT51A	1	T	DQS
F17	PT46B	1	-	-	PT50B	1	-	-
F16	PT45A	1	-	-	PT49A	1	-	-
C16	PT44B	1	C	-	PT48B	1	C	-
D16	PT44A	1	T	-	PT48A	1	T	-
A20	PT43B	1	C	-	PT47B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B20	PT43A	1	T	-	PT47A	1	T	-
A19	PT42B	1	C	-	PT46B	1	C	-
B19	PT42A	1	T	-	PT46A	1	T	-
C15	PT41B	1	C	-	PT45B	1	C	-
D15	PT41A	1	T	-	PT45A	1	T	-
A18	PT40B	1	C	-	PT44B	1	C	-
B18	PT40A	1	T	-	PT44A	1	T	-
F15	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-
E15	PT39A	1	T	DQS	PT43A	1	T	DQS
A17	PT38B	1	-	-	PT42B	1	-	-
B17	PT37A	1	-	-	PT41A	1	-	-
E14	PT36B	1	C	-	PT40B	1	C	-
F14	PT36A	1	T	-	PT40A	1	T	-
D14	PT35B	1	C	-	PT39B	1	C	-
C14	PT35A	1	T	D0	PT39A	1	T	D0
A16	PT34B	1	C	D1	PT38B	1	C	D1
B16	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
A15	PT33B	1	C	-	PT37B	1	C	-
B15	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-
E13	PT32B	1	C	D3	PT36B	1	C	D3
D13	PT32A	1	T	-	PT36A	1	T	-
C13	PT31B	1	C	-	PT35B	1	C	-
B13	PT31A	1	T	DQS	PT35A	1	T	DQS

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4FN388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3FN256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4FN256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4FN484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3FN388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4FN388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3FN256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4FN256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4FN484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3FN388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4FN388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3FN256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4FN256I	188	1.2V	-4	fpBGA	256	IND	19.7K

LatticeXP Family Data Sheet Revision History

November 2007 **Data Sheet DS1001**

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
		DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
			Updated Logic Signal Connections Dual Function column.
		Ordering Information	Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.